

End of Life Plan for

**Kodak i2900, i3200, i3300, i3400, i3250, i3450, i3500
Scanners**

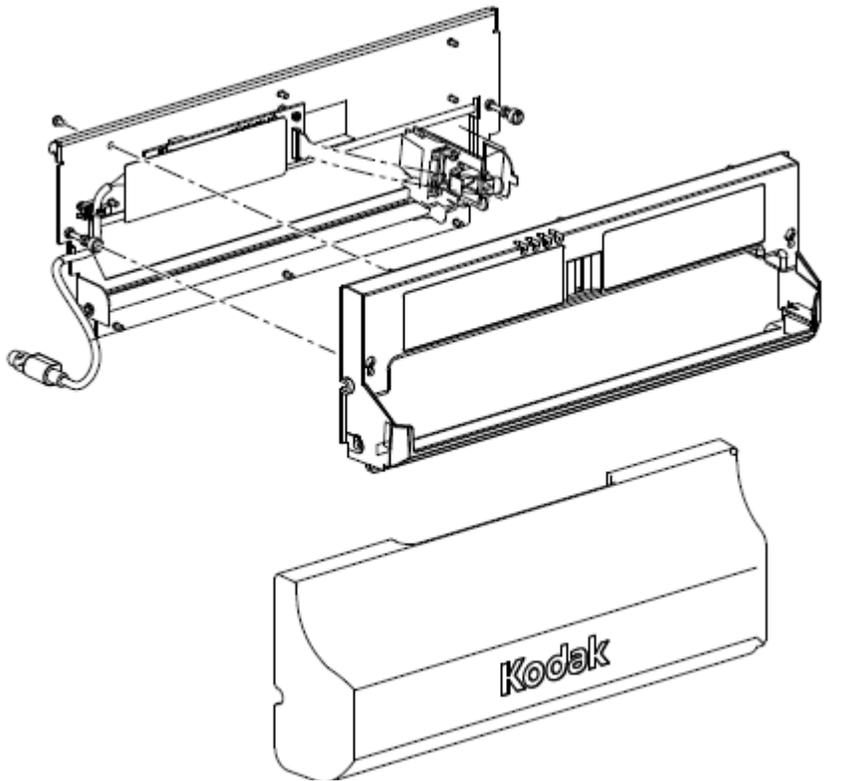
Compositional Analysis

This compositional analysis applies to model(s): i2900, i3200, i3300, i3400, i3250, i3450, i3500 Scanners. The following table identifies the location of materials that need special treatment by recyclers.

Material of concern	Present in part?	Describe Specific Component and/or location
External Battery	no	
Internal Battery	no	
Asbestos	no	
Backlighting lamps with Hg	no	
Beryllium Oxide	no	
Other forms of Beryllium	no	
Cadmium	no	
Capacitors with PCB's	no	
Capacitors with substances of concern and height > 25 mm, diameter > 25 mm or proportionately similar volume	no	
Chromium VI	no	
Gas discharge lamps	no	
Lead (In accordance with EU RoHS exemptions)	yes	i2900 integrated flatbed - motor, Scan Module - lens, resistor, Scanner - die cast frame and clutch power adapter - resistor and pin
Printed Circuit Boards >10 square centimeters		<ul style="list-style-type: none"> • Upper scan module PCB; Figure 2a - e • Lower scan module PCB; Figure 3a - b • LCD operator control panel PCB located upon removing OCP top and side covers. Figure 4a-d • Main PCB is located by removing the right cover, figure 5. • Sensor PCB Figure 6a-b
Liquid Crystal Displays with a surface area > 100cm ²	no	
Mercury	no	
Plastic containing brominated flame retardants	no	
PVC/PVDC	yes	Wire insulation, USB and power cable insulation -connectors - plugs
Radio-active substances	no	

Refractory ceramic fibers	no	
Compartments / units / parts under pressure	no	
Compartments / units / contain liquids	yes	Possible imprinter unit (including PCB) with ink cartridge at rear of scanner can be located by removing the printer cover on the back of the scanner. Figure 1
Compartments / units / contain gasses	no	
Compartments / units / contain "Hidden" mechanical springs or other equivalent parts	no	
Lasers	no	

Figure 1, Remove Printer Accessory cover at rear of scanner



2. Remove Upper scan module PCB, PCB is attached to the side of the scan module assembly.

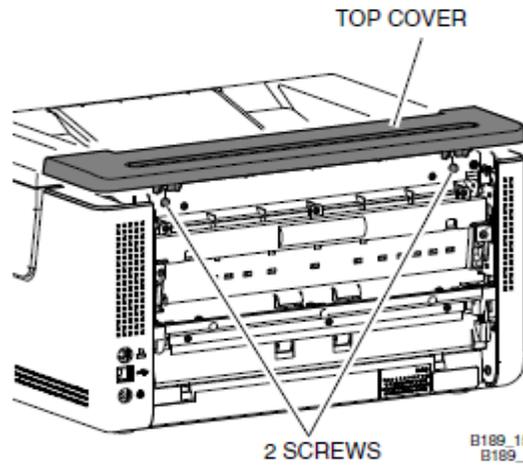
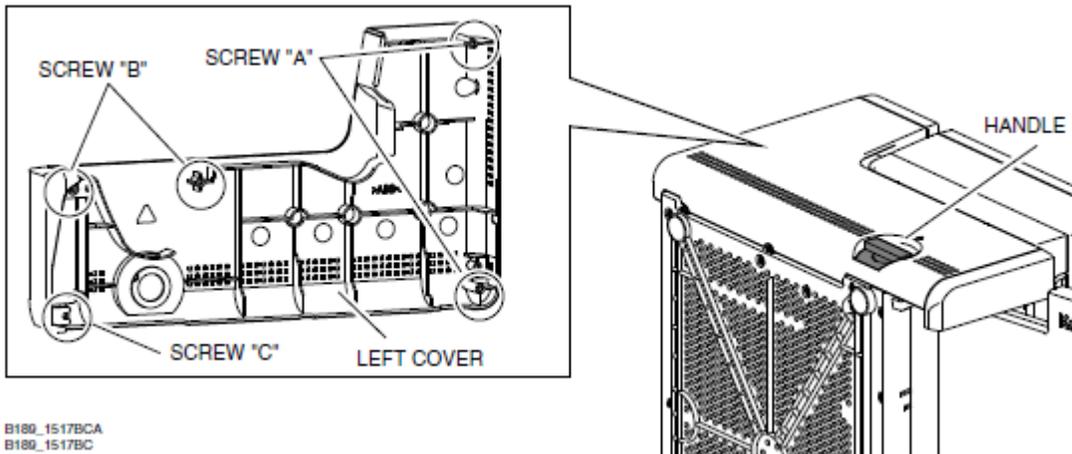


Figure 2a Remove top cover

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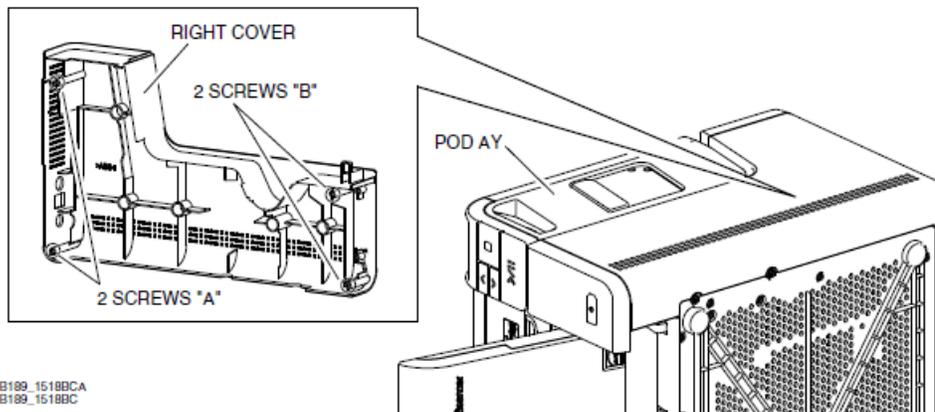
by removing 2 screws as shown.

Figure 2b Remove left cover by removing screws as shown



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B189_1517BC

Figure 2c Remove right cover by removing screws as shown



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B189_1518BC

Figure 2d, for i2900, i3250, and i3450 only, remove the integrated flatbed by removing screws and 2 cables.

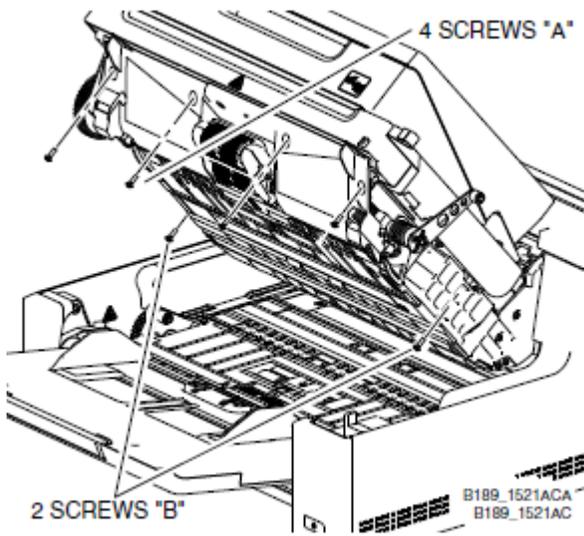


Figure 2e, remove screws, rotate tab, and disconnect cable.

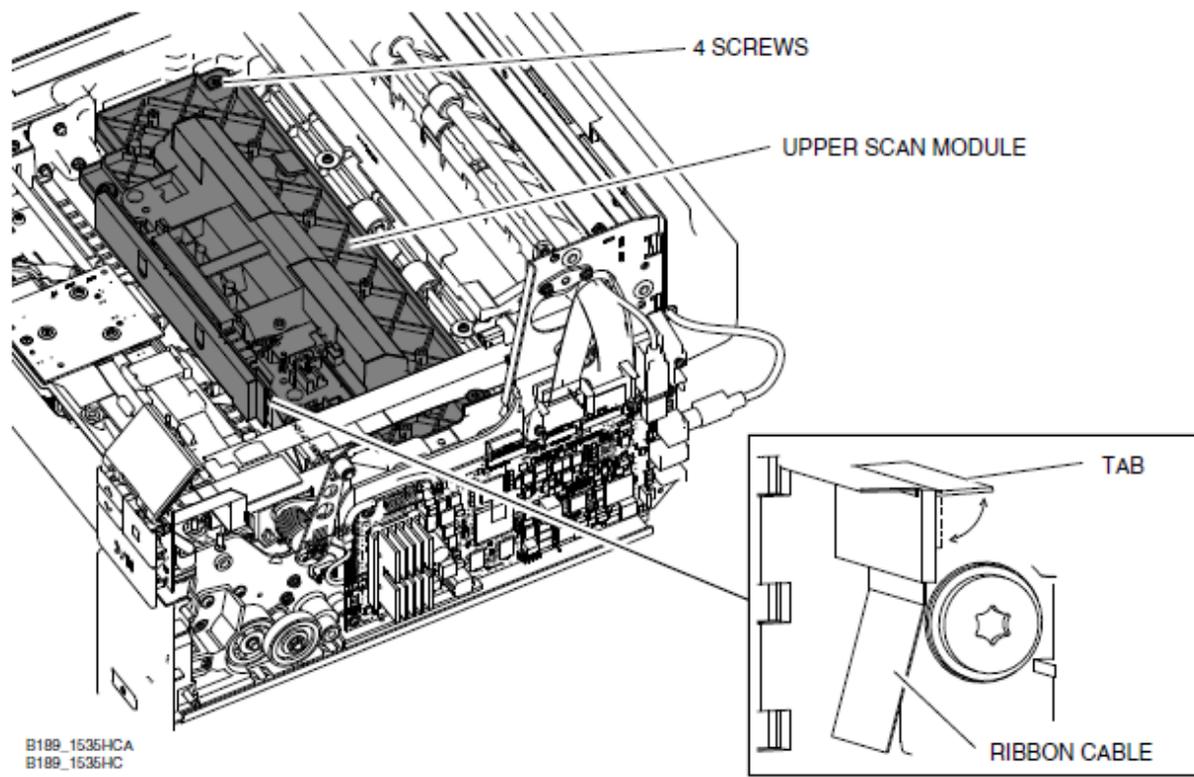


Figure 3a, Remove bottom cover by removing screws as shown

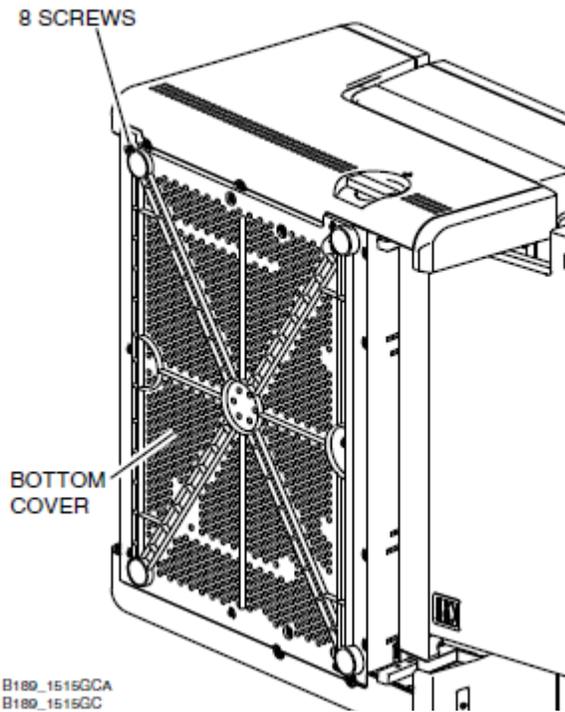


Figure 3b Remove scan module as shown by removing screws and rotating tab as shown.

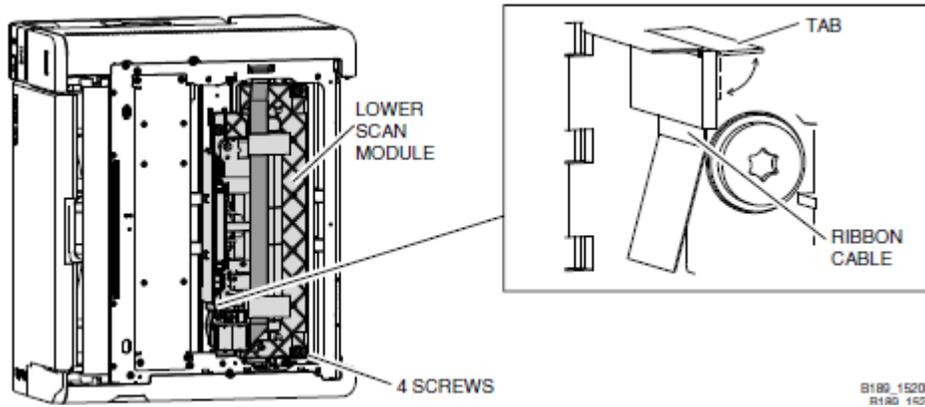


Figure 4a LCD OCP Display assembly

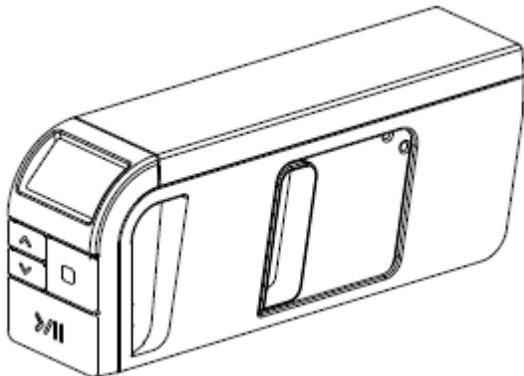
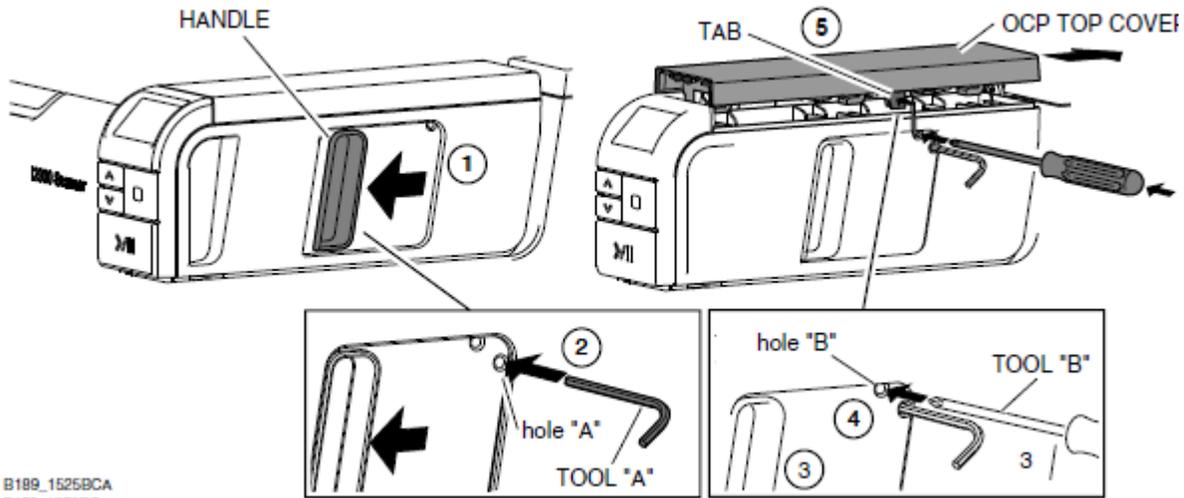


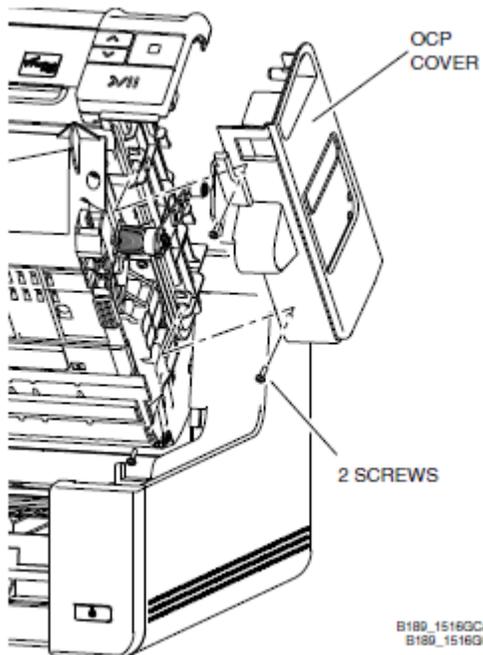
Figure 4b, remove OCP display covers



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B189_1525BC

- 1 Move and hold the HANDLE towards the front.
- 2 Insert a TOOL "A" in hole "A".
- 3 Release the HANDLE.
- 4 Insert and hold a TOOL "B" in hole "B".
- 5 Move the OCP TOP COVER towards the back until it releases.
- 6 Remove the OCP TOP COVER.

Figure 4c, Remove screws from bottom of OCP assembly as shown



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B189_1516GC

Figure 4d, remove clip, cable and screws as shown

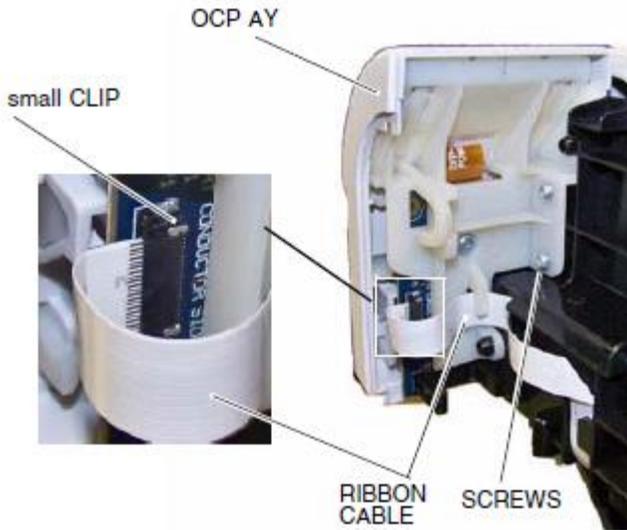


Figure 5, with right cover removed in figure 2c, remove Main PCB as shown.

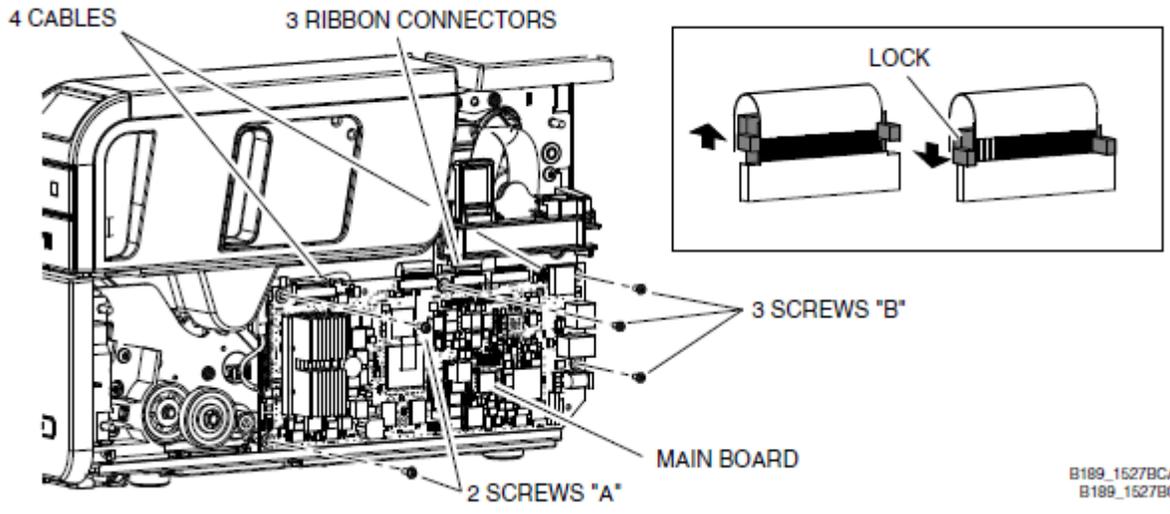


Figure 6a, remove upper baffle as shown to expose sensor PCB.

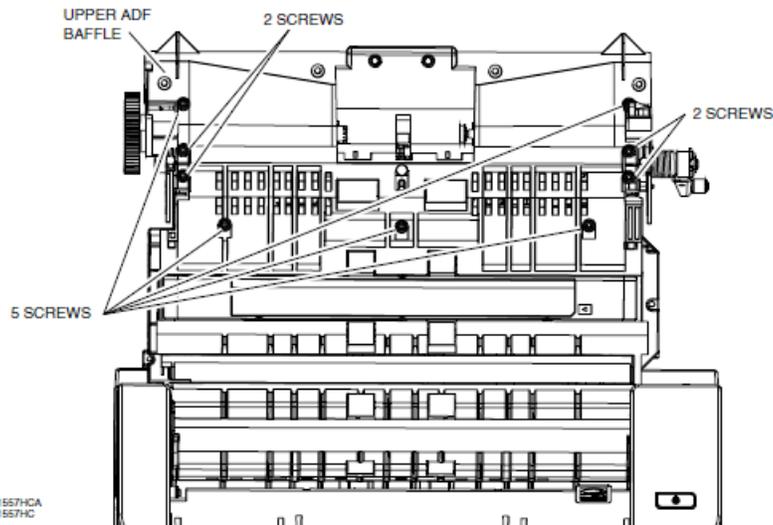
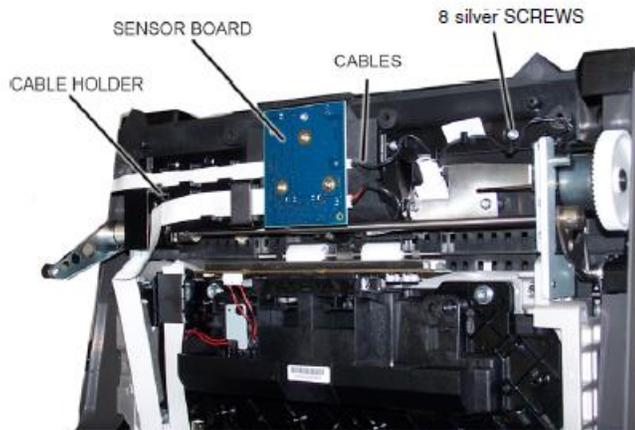


Figure 6b, remove screws and cables as shown



EOL Strategy

The product EOL strategy will be based on market needs, regulations, financial impact, etc. For example, the WEEE Directive in the European Union requires that a collection and treatment infrastructure is in place to manage our products at end-of-life. This obligation will be met through membership in a variety of governmental and industry-led collection schemes, as well as Kodak initiated strategies developed specifically for Kodak products. Strategies such as re-use, re-conditioning, strip and salvage, responsible disposal, etc. can vary by region and change with time.

Regulatory Requirements

The hazardous materials that are contained within this product need to be handled in compliance with the local requirements when discarded by the final user and sent for end-of-life treatment.

For recycler processes; substances, preparations, and components may be removed manually, mechanically, or chemically, metallurgically with the result that hazardous substances, preparation, components are contained in an identifiable waste stream or identifiable part of a waste stream at the end of the treatment process.

- LCDs (liquid crystal displays) must be processed by vendors capable of and experienced in recovering mercury in backlights.
- PC (printed circuit) boards must be processed by a smelter (or other thermal process) capable of and experienced in recovering precious metals (gold and so forth) and heavy metals (lead and so forth) for reuse or by a chemical recovery process. Circuit components may be extracted for reuse prior to smelting.
- Plastics should be recycled for use in new products, components and materials, as substitutes for other raw materials, or recycled in another beneficial manner. When recycling is not economically practical, plastics should be processed for energy recovery at a facility that is designed to control and monitor emissions from the process. See section 14.9 for related information.
- Printing supplies collected as part of hardware recycling (for example, a print cartridge present in a printer at the time of its collection): Original HP printer cartridges must be processed using the HP Inkjet cartridge and LaserJet toner cartridge return and recycling programs in countries where HP programs are available. All other print supplies must be recycled or disposed of in an environmentally responsible manner compliant with applicable laws and regulations.
- Metal (other than in PC boards): Acceptable processing includes liberation of metal items (manually or mechanically), volume reduction for transport (shredding, baling, and so forth), and refining by smelters or foundries (or similar) for the purpose of preparing the metal for reuse. To maximize recycling rates, sending whole products to a smelter is not authorized without approval

from HP and demonstration that the smelter is capable of capturing all of the following for reuse: copper, precious metals (such as gold and silver); steel and aluminum; and, for CRT devices, lead.

- Incineration: If lead-bearing electronic components (such as circuit boards), batteries, polyvinyl chloride (PVC) plastics, mercury lamps, or any material classified as hazardous waste under applicable regulations are disposed of by incineration, the incinerator must meet 99.99% destruction removal efficiency (DRE) for all regulated hazardous contaminants and 99.9999% DRE for dioxins.

The following regulations/directives apply to these products.

WEEE

Equipment Labeling Plans

As per WEEE requirements the equipment is labeled with the dustbin symbol.

Information for Customers and Treatment Facilities

When the last user wishes to discard this product, the information that will guide the customer's action will be available on-line. The disposal information will be made available to the recycler through instructions via Kodak website.

Information provided to the user in the User Manual includes the meaning of the dustbin symbol, instructions not to dispose as unsorted municipal waste, available collection system and their role in contributing to WEEE goals and potential environmental and health effects as a result of the presence of hazardous substances.